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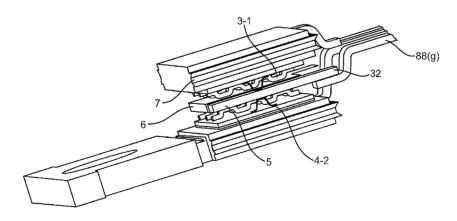
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(54) Title: SEMICONDUCTOR DIE PACKAGE INCLUDING STACKED DICE AND HEAT SINK STRUCTURES



(57) Abstract: A semiconductor package including stacked packages is disclosed. The semiconductor die package includes a first heat sink structure, a first semiconductor die attached to the first heat sink structure and having a first exterior surface, an intermediate conductive element attached to the first semiconductor die, a second semiconductor die attached to the second heat sink structure, and a second heat sink structure attached to the second semiconductor die and comprising a second exterior surface. A molding material is disposed around the first and second semiconductor dice, where the molding material exposes the first exterior surface of the first heat sink structure and exposes the second exterior surface of the second heat sink structure.



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A. CLASSIFICATION OF SUBJECT MATTER IPC(8) - H01L 23/00 (2007.10) USPC - 257/675 According to International Patent Classification (IPC) or to both national classification and IPC			
B. FIELDS SEARCHED			
Minimum documentation searched (classification system followed by classification symbols) IPC(8) - 257/675, 678, 661, 686, 706 USPC - H01L 23/00, 23/34, 23/48, 23/52, 23/16, 23/36 (2007.10)			
Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched			
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)			
MicroPatent, Google Patent Search			
C. DOCUMENTS CONSIDERED TO BE RELEVANT			
Category*	Citation of document, with indication, where ap	propriate, of the relevant passages	Relevant to claim No.
X Y	US 6,559,525 B2 (HUANG) 06 May 2003 (06.05.2003) entire document		1,5,7,9,14-16 2-4, 6, 8, 10-13, 17-18
Y	US 2002/0124955 A1 (TUNG et al) 12 September 2002 (12.09.2002) Sections [0005], [0025], [0026]		2,6,12,13,17
Y	US 7,009,292 B2 (MIURA et al) 07 March 2006 (07.03.2006) col. 9 lines 57-59		3,4,10,11
Y	US 5,323,060 A (FOGAL et al) 21 June 1994 (21.06.1994) col. 1 lines 6-7, col. 2 lines 19-30		8,18
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